

10/675,686

PATENTAMENDMENT AFTER ALLOWANCE IN RESPONSE TO
OFFICE ACTION DATED AUGUST 13, 2004))SPECIFICATION AMENDMENTS

At paragraph 13, please amend the text as follows:

[0013] Figures 2A, 2B and 2C-2A, 2B, 2C and 2D together are a circuit schematic diagram of an RF module with an LTCC substrate in accordance with one embodiment of the presently claimed invention.

At paragraph 14, please amend the text as follows:

[0014] Figure 3 is a circuit schematic diagram of a multiple pole bandpass filter used in the circuit of Figures 2A, 2B and 2C-2A, 2B, 2C and 2D.

At paragraph 15, please amend the text as follows:

[0015] Figures 4A-4H illustrate the eight conductive electrode patterns of the seven layers of an LTCC substrate used to implement the circuit of Figures 2A-2C-2A-2D.

At paragraph 21, please amend the text as follows:

[0021] Referring to Figures 2A-2C-2A-2D together, an RF circuit module with an LTCC substrate in accordance with one embodiment of the presently claimed invention includes two surface-mounted IC chips, IC1, IC2 and a number of various surface-mounted or buried passive support components, i.e., resistors, capacitors and inductors, interconnected substantially as shown, and interfaced with external circuitry by way of an array IO1 of input/output connections. The specific functions and operations performed by the integrated circuits IC1, IC2 will not be described as they are not material to the subject invention. Selected ones of the outlying passive components which are material to the subject invention are discussed in more detail below.

OK
to
Enter
Co
2/28/05

Atty. Docket No.: P05702 (11461.00.5702) - 2 -
CHICAGO/#1271547.1